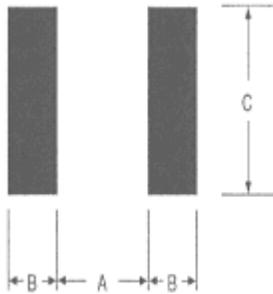


Pad Layouts , Solder Reflow and Rework Recommendation

The dimensions in the table below provide the recommended pad layout for SMD in different footprints.



Pad dimensions (mm)			
Device	A Nominal	B Nominal	C Nominal
All 0603 Series	0.80	0.60	0.80
All 0805 Series	1.20	1.00	1.50
All 1206 Series	2.00	1.00	1.90
All 1210 Series	2.00	1.00	2.80
All 1812 Series	3.45	1.78	3.50
All 2016 Series	3.40	1.50	4.60
All 2920 Series	5.10	2.30	5.60

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (T_{smax} to T_p)	3°C/second max.
Preheat:	
Temperature Min (T _{smin})	150°C
Temperature Max (T _{smax})	200°C
Time (T _{smin} to T _{smax})	16~180 second
Time maintained above :	
Temperature (T _L)	217°C
Time (t _L)	60~150 second
Peak/Classification Temperature (T_p)	260°C
Time within 5C of actual Peak :	
Temperature (t _p)	20~40 second
Ramp-Down Rate	6°C/second max.
Time 25C to Peak Temperature	8 minutes max.

Solder reflow

※ Due to “Lead Free” nature, Temperature and Dwelling Time for the soldering zone is higher than those for Regular. This may cause damage to other components.

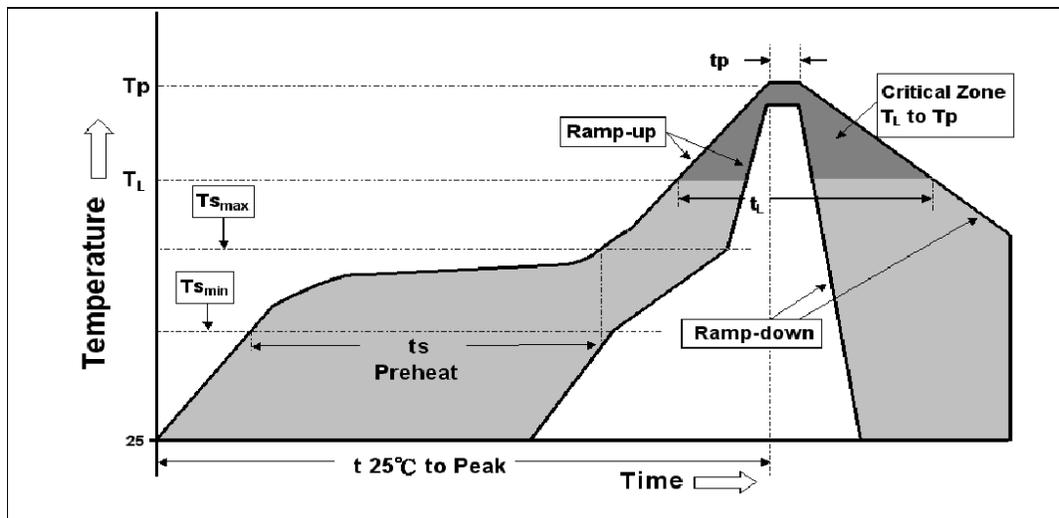
1. Recommended max paste thickness > 0.25mm
2. Devices can be cleaned using standard methods and aqueous solvent.
3. Rework use standard industry practices.
4. Storage Environment : < 30°C / 60% RH

Caution:

1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
2. Devices are not designed to be wave soldered to the bottom side of the board.

Note 1: All temperatures refer to of the package, measured on the package body surface.

Reflow Profile



NOTE: All Specifications subject to change without notice.